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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I ² C, LINbus, SIO, SSU, UART/USART
Peripherals	POR, PWM, Voltage Detect, WDT
Number of I/O	71
Program Memory Size	48KB (48K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2.5K x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 5.5V
Data Converters	A/D 20x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	80-LQFP
Supplier Device Package	80-LQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f212d7snfp-v2

1. Overview

1.1 Features

The R8C/2C Group and R8C/2D Group of single-chip MCUs incorporates the R8C/Tiny Series CPU core, employing sophisticated instructions for a high level of efficiency. With 1 Mbyte of address space, and it is capable of executing instructions at high speed. In addition, the CPU core boasts a multiplier for high-speed operation processing.

Power consumption is low, and the supported operating modes allow additional power control. These MCUs also use an anti-noise configuration to reduce emissions of electromagnetic noise and are designed to withstand EMI.

Integration of many peripheral functions, including multifunction timer and serial interface, reduces the number of system components.

Furthermore, the R8C/2D Group has on-chip data flash (1 KB $\times$ 2 blocks).

The difference between the R8C/2C Group and R8C/2D Group is only the presence or absence of data flash. Their peripheral functions are the same.

1.1.1 Applications

Electronic household appliances, office equipment, audio equipment, consumer equipment, etc.

1.1.2 Specifications

Tables 1.1 and 1.2 outlines the Specifications for R8C/2C Group and Tables 1.3 and 1.4 outlines the Specifications for R8C/2D Group.

Table 1.1 Specifications for R8C/2C Group (1)

Item	Function	Specification
CPU	Central processing unit	R8C/Tiny series core • Number of fundamental instructions: 89 • Minimum instruction execution time: 50 ns ($f(XIN) = 20\text{ MHz}$, $VCC = 3.0\text{ to }5.5\text{ V}$) 100 ns ($f(XIN) = 10\text{ MHz}$, $VCC = 2.7\text{ to }5.5\text{ V}$) 200 ns ($f(XIN) = 5\text{ MHz}$, $VCC = 2.2\text{ to }5.5\text{ V}$) • Multiplier: 16 bits $\times$ 16 bits $\rightarrow$ 32 bits • Multiply-accumulate instruction: 16 bits $\times$ 16 bits + 32 bits $\rightarrow$ 32 bits • Operation mode: Single-chip mode (address space: 1 Mbyte)
Memory	ROM, RAM	Refer to Table 1.5 Product List for R8C/2C Group .
Power Supply Voltage Detection	Voltage detection circuit	• Power-on reset • Voltage detection 3
I/O Ports	Programmable I/O ports	• Input-only: 2 pins • CMOS I/O ports: 71, selectable pull-up resistor • High current drive ports: 8
Clock	Clock generation circuits	3 circuits: XIN clock oscillation circuit (with on-chip feedback resistor), On-chip oscillator (high-speed, low-speed) (high-speed on-chip oscillator has a frequency adjustment function), XCIN clock oscillation circuit (32 kHz) • Oscillation stop detection: XIN clock oscillation stop detection function • Frequency divider circuit: Dividing selectable 1, 2, 4, 8, and 16 • Low power consumption modes: - Standard operating mode (high-speed clock, low-speed clock, high-speed on-chip oscillator, low-speed on-chip oscillator), wait mode, stop mode
		Real-time clock (timer RE)
Interrupts		• External: 5 sources, Internal: 23 sources, Software: 4 sources • Priority levels: 7 levels
Watchdog Timer		15 bits $\times$ 1 (with prescaler), reset start selectable
Timer	Timer RA	8 bits $\times$ 1 (with 8-bit prescaler) Timer mode (period timer), pulse output mode (output level inverted every period), event counter mode, pulse width measurement mode, pulse period measurement mode
	Timer RB	8 bits $\times$ 1 (with 8-bit prescaler) Timer mode (period timer), programmable waveform generation mode (PWM output), programmable one-shot generation mode, programmable wait one-shot generation mode
	Timer RC	16 bits $\times$ 1 (with 4 capture/compare registers) Timer mode (input capture function, output compare function), PWM mode (output 3 pins), PWM2 mode (PWM output pin)
	Timer RD	16 bits $\times$ 2 (with 4 capture/compare registers) Timer mode (input capture function, output compare function), PWM mode (output 6 pins), reset synchronous PWM mode (output three-phase waveforms (6 pins), sawtooth wave modulation), complementary PWM mode (output three-phase waveforms (6 pins), triangular wave modulation), PWM3 mode (PWM output 2 pins with fixed period)
	Timer RE	8 bits $\times$ 1 Real-time clock mode (count seconds, minutes, hours, days of week), output compare mode
	Timer RF	16 bits $\times$ 1 (with capture/compare register pin and compare register pin) Input capture mode, output compare mode

1.2 Product List

Table 1.5 lists Product List for R8C/2C Group, Figure 1.1 shows a Part Number, Memory Size, and Package of R8C/2C Group, Table 1.6 lists Product List for R8C/2D Group, and Figure 1.2 shows a Part Number, Memory Size, and Package of R8C/2D Group.

Table 1.5 Product List for R8C/2C Group

Current of Dec. 2007

Part No.	ROM Capacity	RAM Capacity	Package Type	Remarks		
R5F212C7SNFP	48 Kbytes	2.5 Kbytes	PLQP0080KB-A	N version		
R5F212C8SNFP	64 Kbytes	3 Kbytes	PLQP0080KB-A			
R5F212CASNFP	96 Kbytes	7 Kbytes	PLQP0080KB-A			
R5F212CCSNFP	128 Kbytes	7.5 Kbytes	PLQP0080KB-A			
R5F212C7SDFP	48 Kbytes	2.5 Kbytes	PLQP0080KB-A	D version		
R5F212C8SDFP	64 Kbytes	3 Kbytes	PLQP0080KB-A			
R5F212CASDFP	96 Kbytes	7 Kbytes	PLQP0080KB-A			
R5F212CCSDFP	128 Kbytes	7.5 Kbytes	PLQP0080KB-A			
R5F212C7SNXXXFP	48 Kbytes	2.5 Kbytes	PLQP0080KB-A	N version	Factory programming product ⁽¹⁾	
R5F212C8SNXXXFP	64 Kbytes	3 Kbytes	PLQP0080KB-A			
R5F212CASNXXXFP	96 Kbytes	7 Kbytes	PLQP0080KB-A			
R5F212CCSNXXXFP	128 Kbytes	7.5 Kbytes	PLQP0080KB-A			
R5F212C7SDXXXFP	48 Kbytes	2.5 Kbytes	PLQP0080KB-A	D version		
R5F212C8SDXXXFP	64 Kbytes	3 Kbytes	PLQP0080KB-A			
R5F212CASDXXXFP	96 Kbytes	7 Kbytes	PLQP0080KB-A			
R5F212CCSDXXXFP	128 Kbytes	7.5 Kbytes	PLQP0080KB-A			

NOTE:

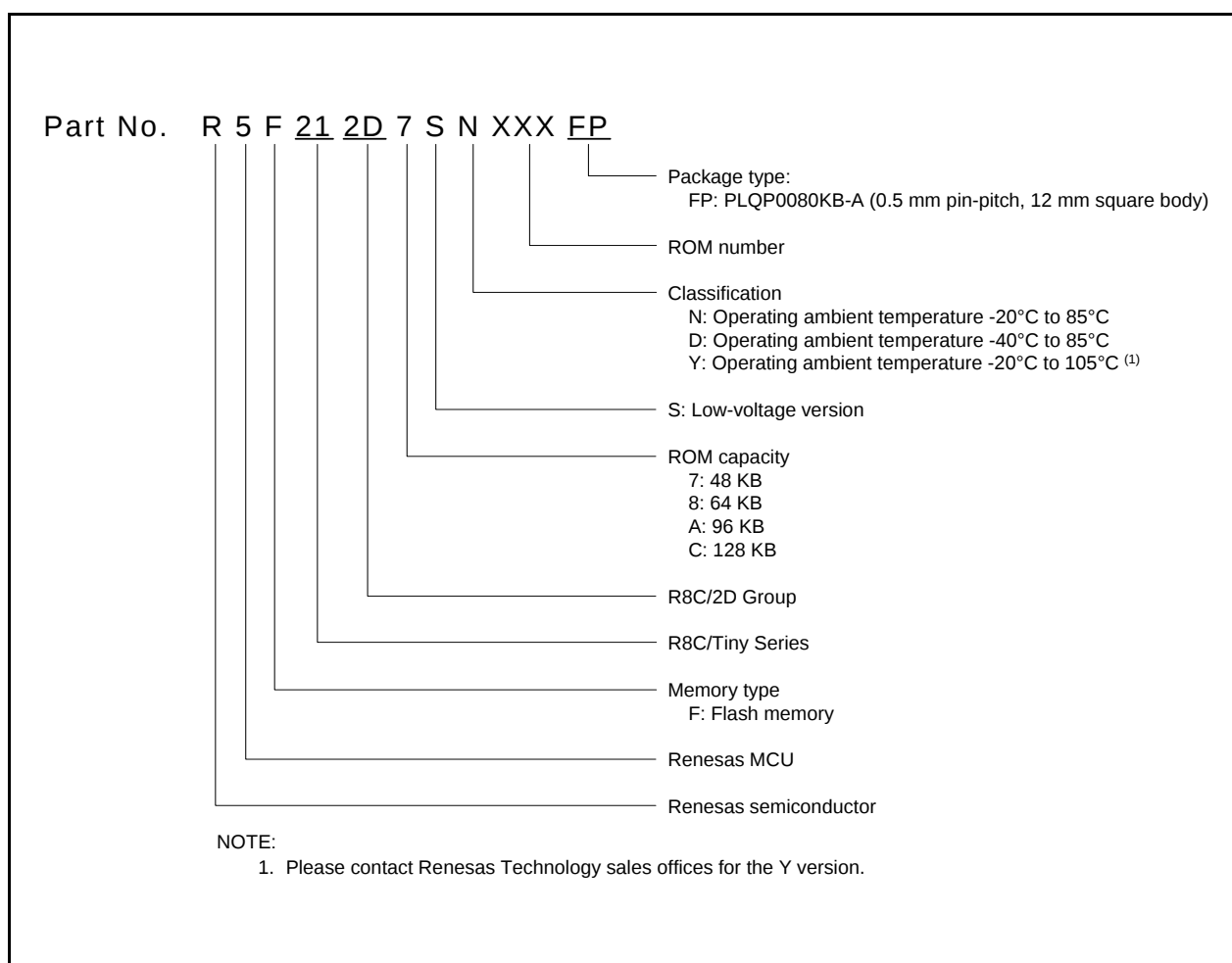
1. The user ROM is programmed before shipment.

Table 1.6 Product List for R8C/2D Group**Current of Dec. 2007**

Part No.	ROM Capacity		RAM Capacity	Package Type	Remarks		
	Program ROM	Data flash					
R5F212D7SNFP	48 Kbytes	1 Kbyte × 2	2.5 Kbytes	PLQP0080KB-A	N version		
R5F212D8SNFP	64 Kbytes	1 Kbyte × 2	3 Kbytes	PLQP0080KB-A			
R5F212DASNFP	96 Kbytes	1 Kbyte × 2	7 Kbytes	PLQP0080KB-A			
R5F212DCSNFP	128 Kbytes	1 Kbyte × 2	7.5 Kbytes	PLQP0080KB-A			
R5F212D7SDFP	48 Kbytes	1 Kbyte × 2	2.5 Kbytes	PLQP0080KB-A	D version		
R5F212D8SDFP	64 Kbytes	1 Kbyte × 2	3 Kbytes	PLQP0080KB-A			
R5F212DASDFP	96 Kbytes	1 Kbyte × 2	7 Kbytes	PLQP0080KB-A			
R5F212DCSDFP	128 Kbytes	1 Kbyte × 2	7.5 Kbytes	PLQP0080KB-A			
R5F212D7SNXXXFP	48 Kbytes	1 Kbyte × 2	2.5 Kbytes	PLQP0080KB-A	N version	Factory programming product ⁽¹⁾	
R5F212D8SNXXXFP	64 Kbytes	1 Kbyte × 2	3 Kbytes	PLQP0080KB-A			
R5F212DASNXXXFP	96 Kbytes	1 Kbyte × 2	7 Kbytes	PLQP0080KB-A			
R5F212DCSNXXXFP	128 Kbytes	1 Kbyte × 2	7.5 Kbytes	PLQP0080KB-A			
R5F212D7SDXXXFP	48 Kbytes	1 Kbyte × 2	2.5 Kbytes	PLQP0080KB-A	D version		
R5F212D8SDXXXFP	64 Kbytes	1 Kbyte × 2	3 Kbytes	PLQP0080KB-A			
R5F212DASDXXXFP	96 Kbytes	1 Kbyte × 2	7 Kbytes	PLQP0080KB-A			
R5F212DCSDXXXFP	128 Kbytes	1 Kbyte × 2	7.5 Kbytes	PLQP0080KB-A			

NOTE:

1. The user ROM is programmed before shipment.

**Figure 1.2 Part Number, Memory Size, and Package of R8C/2D Group**

2.1 Data Registers (R0, R1, R2, and R3)

R0 is a 16-bit register for transfer, arithmetic, and logic operations. The same applies to R1 to R3. R0 can be split into high-order bits (R0H) and low-order bits (R0L) to be used separately as 8-bit data registers. R1H and R1L are analogous to R0H and R0L. R2 can be combined with R0 and used as a 32-bit data register (R2R0). R3R1 is analogous to R2R0.

2.2 Address Registers (A0 and A1)

A0 is a 16-bit register for address register indirect addressing and address register relative addressing. It is also used for transfer, arithmetic, and logic operations. A1 is analogous to A0. A1 can be combined with A0 and as a 32-bit address register (A1A0).

2.3 Frame Base Register (FB)

FB is a 16-bit register for FB relative addressing.

2.4 Interrupt Table Register (INTB)

INTB is a 20-bit register that indicates the start address of an interrupt vector table.

2.5 Program Counter (PC)

PC is 20 bits wide and indicates the address of the next instruction to be executed.

2.6 User Stack Pointer (USP) and Interrupt Stack Pointer (ISP)

The stack pointers (SP), USP, and ISP, are each 16 bits wide. The U flag of FLG is used to switch between USP and ISP.

2.7 Static Base Register (SB)

SB is a 16-bit register for SB relative addressing.

2.8 Flag Register (FLG)

FLG is an 11-bit register indicating the CPU state.

2.8.1 Carry Flag (C)

The C flag retains carry, borrow, or shift-out bits that have been generated by the arithmetic and logic unit.

2.8.2 Debug Flag (D)

The D flag is for debugging only. Set it to 0.

2.8.3 Zero Flag (Z)

The Z flag is set to 1 when an arithmetic operation results in 0; otherwise to 0.

2.8.4 Sign Flag (S)

The S flag is set to 1 when an arithmetic operation results in a negative value; otherwise to 0.

2.8.5 Register Bank Select Flag (B)

Register bank 0 is selected when the B flag is 0. Register bank 1 is selected when this flag is set to 1.

2.8.6 Overflow Flag (O)

The O flag is set to 1 when an operation results in an overflow; otherwise to 0.

3.2 R8C/2D Group

Figure 3.2 is a Memory Map of R8C/2D Group. The R8C/2D group has 1 Mbyte of address space from addresses 00000h to FFFFFh.

The internal ROM (program ROM) is allocated lower addresses, beginning with address 0FFFFh. For example, a 48-Kbyte internal ROM area is allocated addresses 04000h to 0FFFFh.

The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. They store the starting address of each interrupt routine.

The internal ROM (data flash) is allocated addresses 02400h to 02BFFh.

The internal RAM area is allocated higher addresses, beginning with address 00400h. For example, a 2.5-Kbyte internal RAM is allocated addresses 00400h to 00DFFh. The internal RAM is used not only for storing data but also for calling subroutines and as stacks when interrupt requests are acknowledged.

Special function registers (SFRs) are allocated addresses 00000h to 002FFh. The peripheral function control registers are allocated here. All addresses within the SFR, which have nothing allocated are reserved for future use and cannot be accessed by users.

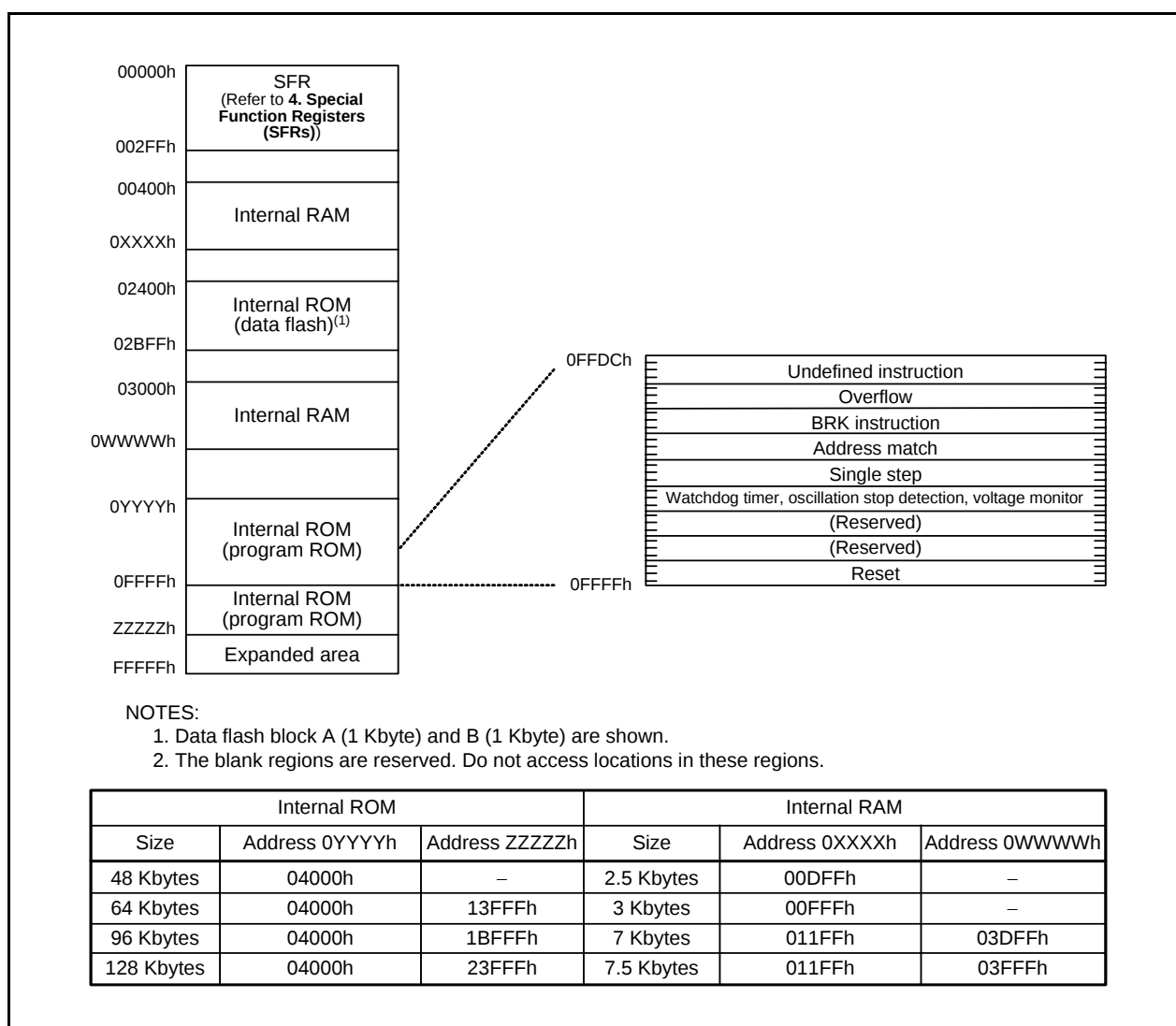


Figure 3.2 Memory Map of R8C/2D Group

4. Special Function Registers (SFRs)

An SFR (special function register) is a control register for a peripheral function. Tables 4.1 to 4.12 list the special function registers.

Table 4.1 SFR Information (1)(1)

Address	Register	Symbol	After reset
0000h			
0001h			
0002h			
0003h			
0004h	Processor Mode Register 0	PM0	00h
0005h	Processor Mode Register 1	PM1	00h
0006h	System Clock Control Register 0	CM0	01101000b
0007h	System Clock Control Register 1	CM1	00100000b
0008h	Module Operation Enable Register	MSTCR	00h
0009h			
000Ah	Protect Register	PRCR	00h
000Bh			
000Ch	Oscillation Stop Detection Register	OCD	00000100b
000Dh	Watchdog Timer Reset Register	WDTR	XXh
000Eh	Watchdog Timer Start Register	WDTS	XXh
000Fh	Watchdog Timer Control Register	WDC	00X11111b
0010h	Address Match Interrupt Register 0	RMAD0	00h
0011h			00h
0012h			00h
0013h	Address Match Interrupt Enable Register	AIER	00h
0014h	Address Match Interrupt Register 1	RMAD1	00h
0015h			00h
0016h			00h
0017h			
0018h			
0019h			
001Ah			
001Bh			
001Ch	Count Source Protection Mode Register	CSPR	00h 10000000b ⁽⁶⁾
001Dh			
001Eh			
001Fh			
0020h			
0021h			
0022h			
0023h	High-Speed On-Chip Oscillator Control Register 0	FRA0	00h
0024h	High-Speed On-Chip Oscillator Control Register 1	FRA1	When shipping
0025h	High-Speed On-Chip Oscillator Control Register 2	FRA2	00h
0026h			
0027h			
0028h	Clock Prescaler Reset Flag	CPSRF	00h
0029h			
002Ah			
002Bh	High-Speed On-Chip Oscillator Control Register 6	FRA6	When Shipping
002Ch	High-Speed On-Chip Oscillator Control Register 7	FRA7	When Shipping
0030h			
0031h	Voltage Detection Register 1 ⁽²⁾	VCA1	00001000b
0032h	Voltage Detection Register 2 ⁽²⁾	VCA2	00h ⁽³⁾ 00100000b ⁽⁴⁾
0033h			
0034h			
0035h			
0036h	Voltage Monitor 1 Circuit Control Register ⁽⁵⁾	VW1C	00001000b
0037h	Voltage Monitor 2 Circuit Control Register ⁽⁵⁾	VW2C	00h
0038h	Voltage Monitor 0 Circuit Control Register ⁽²⁾	VW0C	0000X000b ⁽³⁾ 0100X001b ⁽⁴⁾
0039h			
003Ah			
003Eh			
003Fh			

X: Undefined

NOTES:

- The blank regions are reserved. Do not access locations in these regions.
- Software reset, watchdog timer reset, voltage monitor 1 reset, or voltage monitor 2 reset do not affect this register.
- The LVD0ON bit in the OFS register is set to 1 and hardware reset.
- Power-on reset, voltage monitor 0 reset, or the LVD0ON bit in the OFS register is set to 0 and hardware reset.
- Software reset, watchdog timer reset, voltage monitor 1 reset, or voltage monitor 2 reset do not affect b2 and b3.
- The CSPROINI bit in the OFS register is set to 0.

Table 4.5 SFR Information (5)⁽¹⁾

Address	Register	Symbol	After reset
0100h	Timer RA Control Register	TRACR	00h
0101h	Timer RA I/O Control Register	TRAIOC	00h
0102h	Timer RA Mode Register	TRAMR	00h
0103h	Timer RA Prescaler Register	TRAPRE	FFh
0104h	Timer RA Register	TRA	FFh
0105h	LIN Control Register 2	LINCR2	00h
0106h	LIN Control Register	LINCR	00h
0107h	LIN Status Register	LINST	00h
0108h	Timer RB Control Register	TRBCR	00h
0109h	Timer RB One-Shot Control Register	TRBOCR	00h
010Ah	Timer RB I/O Control Register	TRBIOC	00h
010Bh	Timer RB Mode Register	TRBMR	00h
010Ch	Timer RB Prescaler Register	TRBPRES	FFh
010Dh	Timer RB Secondary Register	TRBSC	FFh
010Eh	Timer RB Primary Register	TRBPR	FFh
010Fh			
0110h			
0111h			
0112h			
0113h			
0114h			
0115h			
0116h			
0117h			
0118h	Timer RE Second Data Register / Counter Data Register	TRESEC	00h
0119h	Timer RE Minute Data Register / Compare Data Register	TREMIN	00h
011Ah	Timer RE Hour Data Register	TREHR	00h
011Bh	Timer RE Day of Week Data Register	TREWK	00h
011Ch	Timer RE Control Register 1	TRECR1	00h
011Dh	Timer RE Control Register 2	TRECR2	00h
011Eh	Timer RE Clock Source Select Register	TRECSR	00001000b
011Fh			
0120h	Timer RC Mode Register	TRCMR	01001000b
0121h	Timer RC Control Register 1	TRCCR1	00h
0122h	Timer RC Interrupt Enable Register	TRCIER	01110000b
0123h	Timer RC Status Register	TRCSR	01110000b
0124h	Timer RC I/O Control Register 0	TRCIOR0	10001000b
0125h	Timer RC I/O Control Register 1	TRCIOR1	10001000b
0126h	Timer RC Counter	TRC	00h
0127h			00h
0128h	Timer RC General Register A	TRCGRA	FFh
0129h			FFh
012Ah	Timer RC General Register B	TRCGRB	FFh
012Bh			FFh
012Ch	Timer RC General Register C	TRCGRC	FFh
012Dh			FFh
012Eh	Timer RC General Register D	TRCGRD	FFh
012Fh			FFh
0130h	Timer RC Control Register 2	TRCCR2	00011111b
0131h	Timer RC Digital Filter Function Select Register	TRCDF	00h
0132h	Timer RC Output Master Enable Register	TRCOER	01111111b
0133h			
0134h			
0135h			
0136h			
0137h	Timer RD Start Register	TRDSTR	11111100b
0138h	Timer RD Mode Register	TRDMR	00001110b
0139h	Timer RD PWM Mode Register	TRDPMR	10001000b
013Ah	Timer RD Function Control Register	TRDFCR	10000000b
013Bh	Timer RD Output Master Enable Register 1	TRDOER1	FFh
013Ch	Timer RD Output Master Enable Register 2	TRDOER2	01111111b
013Dh	Timer RD Output Control Register	TRDOCR	00h
013Eh	Timer RD Digital Filter Function Select Register 0	TRDDF0	00h
013Fh	Timer RD Digital Filter Function Select Register 1	TRDDF1	00h

NOTE:

1. The blank regions are reserved. Do not access locations in these regions

Table 4.6 SFR Information (6)⁽¹⁾

Address	Register	Symbol	After reset
0140h	Timer RD Control Register 0	TRDCR0	00h
0141h	Timer RD I/O Control Register A0	TRDIOA0	10001000b
0142h	Timer RD I/O Control Register C0	TRDIORC0	10001000b
0143h	Timer RD Status Register 0	TRDSR0	11000000b
0144h	Timer RD Interrupt Enable Register 0	TRDIER0	11100000b
0145h	Timer RD PWM Mode Output Level Control Register 0	TRDPOCR0	11111000b
0146h	Timer RD Counter 0	TRD0	00h
0147h			00h
0148h	Timer RD General Register A0	TRDGRA0	FFh
0149h			FFh
014Ah	Timer RD General Register B0	TRDGRB0	FFh
014Bh			FFh
014Ch	Timer RD General Register C0	TRDGRC0	FFh
014Dh			FFh
014Eh	Timer RD General Register D0	TRDGRD0	FFh
014Fh			FFh
0150h	Timer RD Control Register 1	TRDCR1	00h
0151h	Timer RD I/O Control Register A1	TRDIOA1	10001000b
0152h	Timer RD I/O Control Register C1	TRDIORC1	10001000b
0153h	Timer RD Status Register 1	TRDSR1	11000000b
0154h	Timer RD Interrupt Enable Register 1	TRDIER1	11100000b
0155h	Timer RD PWM Mode Output Level Control Register 1	TRDPOCR1	11111000b
0156h	Timer RD Counter 1	TRD1	00h
0157h			00h
0158h	Timer RD General Register A1	TRDGRA1	FFh
0159h			FFh
015Ah	Timer RD General Register B1	TRDGRB1	FFh
015Bh			FFh
015Ch	Timer RD General Register C1	TRDGRC1	FFh
015Dh			FFh
015Eh	Timer RD General Register D1	TRDGRD1	FFh
015Fh			FFh
0160h	UART2 Transmit/Receive Mode Register	U2MR	00h
0161h	UART2 Bit Rate Register	U2BRG	XXh
0162h	UART2 Transmit Buffer Register	U2TB	XXh
0163h			XXh
0164h	UART2 Transmit/Receive Control Register 0	U2C0	00001000b
0165h	UART2 Transmit/Receive Control Register 1	U2C1	00000010b
0166h	UART2 Receive Buffer Register	U2RB	XXh
0167h			XXh
0168h			
0169h			
016Ah			
016Bh			
016Ch			
016Dh			
016Eh			
016Fh			
0170h			
0171h			
0172h			
0173h			
0174h			
0175h			
0176h			
0177h			
0178h			
0179h			
017Ah			
017Bh			
017Ch			
017Dh			
017Eh			
017Fh			

X: Undefined

NOTE:

1. The blank regions are reserved. Do not access locations in these regions.

Table 5.2 Recommended Operating Conditions

Symbol	Parameter		Conditions	Standard			Unit
				Min.	Typ.	Max.	
V _{CC} /AV _{CC}	Supply voltage			2.2	–	5.5	V
V _{SS} /AV _{SS}	Supply voltage			–	0	–	V
V _{IH}	Input “H” voltage			0.8 V _{CC}	–	V _{CC}	V
V _{IL}	Input “L” voltage			0	–	0.2 V _{CC}	V
I _{OH} (sum)	Peak sum output “H” current	Sum of all pins I _{OH} (peak)		–	–	–240	mA
I _{OH} (sum)	Average sum output “H” current	Sum of all pins I _{OH} (avg)		–	–	–120	mA
I _{OH} (peak)	Peak output “H” current	Except P2_0 to P2_7		–	–	–10	mA
		P2_0 to P2_7		–	–	–40	mA
I _{OH} (avg)	Average output “H” current	Except P2_0 to P2_7		–	–	–5	mA
		P2_0 to P2_7		–	–	–20	mA
I _{OL} (sum)	Peak sum output “L” current	Sum of all pins I _{OL} (peak)		–	–	240	mA
I _{OL} (sum)	Average sum output “L” current	Sum of all pins I _{OL} (avg)		–	–	120	mA
I _{OL} (peak)	Peak output “L” current	Except P2_0 to P2_7		–	–	10	mA
		P2_0 to P2_7		–	–	40	mA
I _{OL} (avg)	Average output “L” current	Except P2_0 to P2_7		–	–	5	mA
		P2_0 to P2_7		–	–	20	mA
f _(XIN)	XIN clock input oscillation frequency		3.0 V ≤ V _{CC} ≤ 5.5 V	0	–	20	MHz
			2.7 V ≤ V _{CC} < 3.0 V	0	–	10	MHz
			2.2 V ≤ V _{CC} < 2.7 V	0	–	5	MHz
f _(XCIN)	XCIN clock input oscillation frequency		2.2 V ≤ V _{CC} ≤ 5.5 V	0	–	70	kHz
–	System clock	OCD2 = 0 XIN clock selected	3.0 V ≤ V _{CC} ≤ 5.5 V	0	–	20	MHz
			2.7 V ≤ V _{CC} < 3.0 V	0	–	10	MHz
			2.2 V ≤ V _{CC} < 2.7 V	0	–	5	MHz
		OCD2 = 1 On-chip oscillator clock selected	FRA01 = 0 Low-speed on-chip oscillator clock selected	–	125	–	kHz
			FRA01 = 1 High-speed on-chip oscillator clock selected 3.0 V ≤ V _{CC} ≤ 5.5 V	–	–	20	MHz
			FRA01 = 1 High-speed on-chip oscillator clock selected 2.7 V ≤ V _{CC} ≤ 5.5 V	–	–	10	MHz
			FRA01 = 1 High-speed on-chip oscillator clock selected 2.2 V ≤ V _{CC} ≤ 5.5 V	–	–	5	MHz

NOTES:

1. V_{CC} = 2.2 to 5.5 V at T_{opr} = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.
2. The average output current indicates the average value of current measured during 100 ms.

Table 5.5 Flash Memory (Program ROM) Electrical Characteristics

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
–	Program/erase endurance ⁽²⁾	R8C/2C Group	100 ⁽³⁾	–	–	times
		R8C/2D Group	1,000 ⁽³⁾	–	–	times
–	Byte program time		–	50	400	μs
–	Block erase time		–	0.4	9	s
t _d (SR-SUS)	Time delay from suspend request until suspend		–	–	97+CPU clock × 6 cycles	μs
–	Interval from erase start/restart until following suspend request		650	–	–	μs
–	Interval from program start/restart until following suspend request		0	–	–	ns
–	Time from suspend until program/erase restart		–	–	3+CPU clock × 4 cycles	μs
–	Program, erase voltage		2.7	–	5.5	V
–	Read voltage		2.2	–	5.5	V
–	Program, erase temperature		0	–	60	°C
–	Data hold time ⁽⁷⁾	Ambient temperature = 55°C	20	–	–	year

NOTES:

1. V_{CC} = 2.7 to 5.5 V at T_{opr} = 0 to 60°C, unless otherwise specified.

2. Definition of programming/erasure endurance

The programming and erasure endurance is defined on a per-block basis.

If the programming and erasure endurance is n (n = 100 or 10,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.

However, the same address must not be programmed more than once per erase operation (overwriting prohibited).

3. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).

4. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. It is also advisable to retain data on the erase count of each block and limit the number of erase operations to a certain number.

5. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.

6. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.

7. The data hold time includes time that the power supply is off or the clock is not supplied.

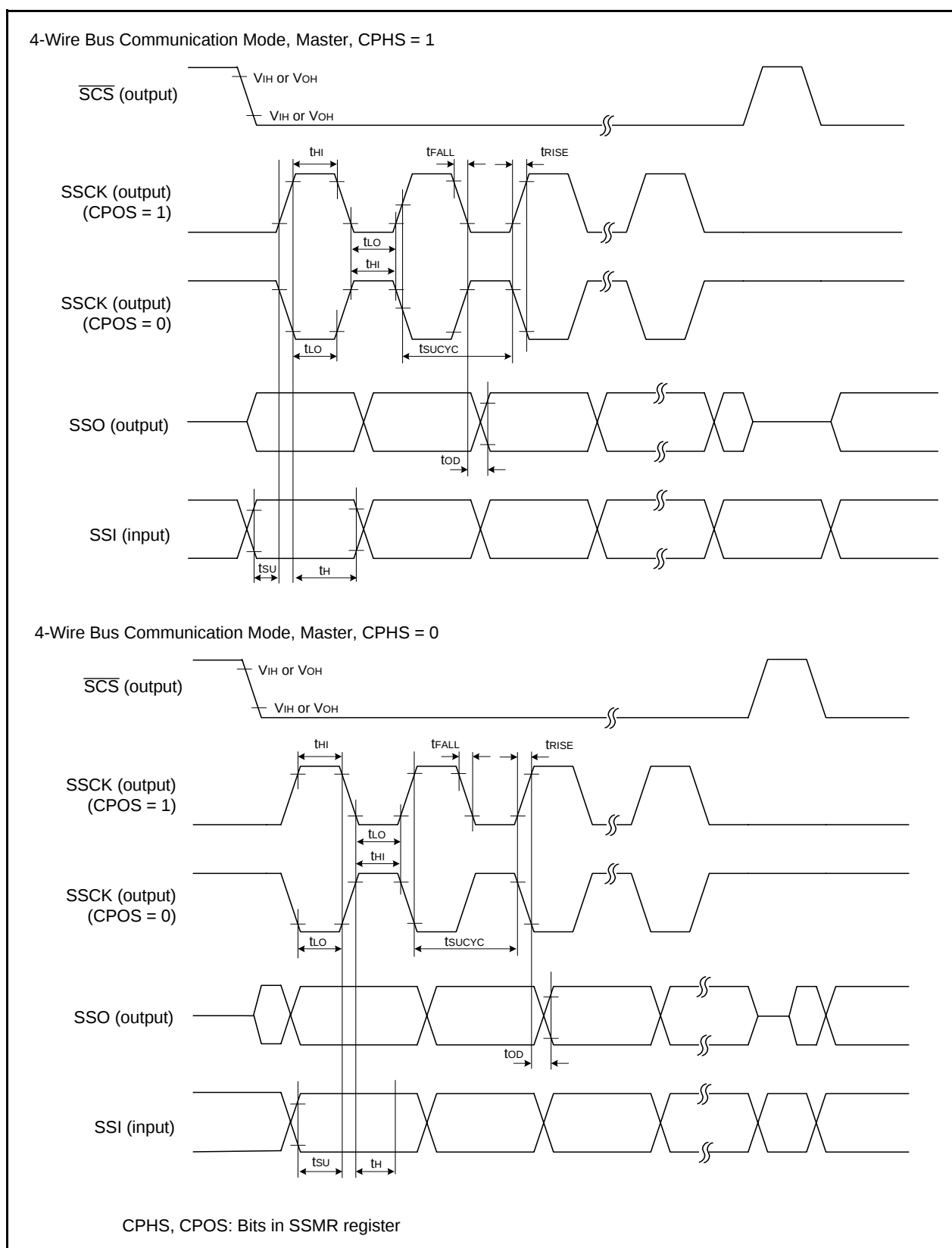


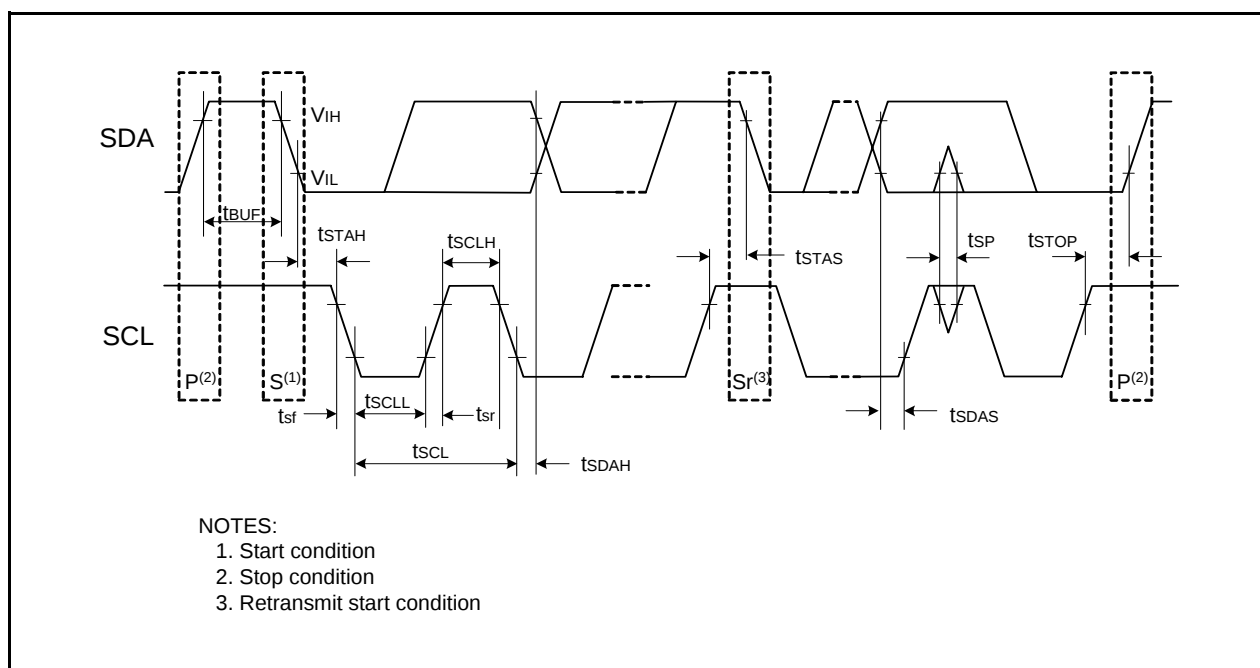
Figure 5.4 I/O Timing of Clock Synchronous Serial I/O with Chip Select (Master)

Table 5.15 Timing Requirements of I²C bus Interface (1)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
t _{SCL}	SCL input cycle time		12t _{cy} c + 600 ⁽²⁾	–	–	ns
t _{SCLH}	SCL input “H” width		3t _{cy} c + 300 ⁽²⁾	–	–	ns
t _{SCLL}	SCL input “L” width		5t _{cy} c + 500 ⁽²⁾	–	–	ns
t _{sf}	SCL, SDA input fall time		–	–	300	ns
t _{SP}	SCL, SDA input spike pulse rejection time		–	–	1t _{cy} c ⁽²⁾	ns
t _{BUF}	SDA input bus-free time		5t _{cy} c ⁽²⁾	–	–	ns
t _{STAH}	Start condition input hold time		3t _{cy} c ⁽²⁾	–	–	ns
t _{STAS}	Retransmit start condition input setup time		3t _{cy} c ⁽²⁾	–	–	ns
t _{STOP}	Stop condition input setup time		3t _{cy} c ⁽²⁾	–	–	ns
t _{SDAS}	Data input setup time		1t _{cy} c + 20 ⁽²⁾	–	–	ns
t _{SDAH}	Data input hold time		0	–	–	ns

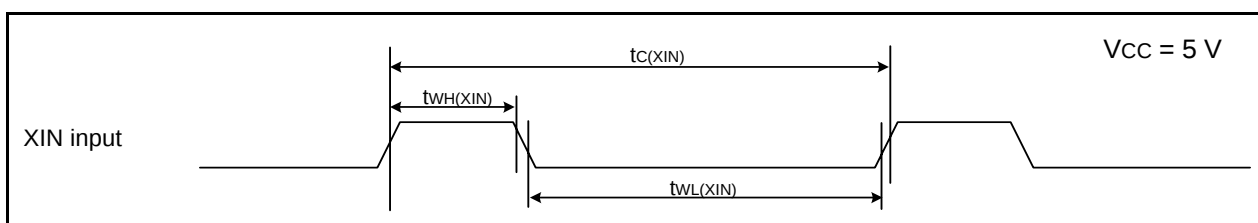
NOTES:

1. V_{CC} = 2.2 to 5.5 V, V_{SS} = 0 V and T_{opr} = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.
2. 1t_{cy}c = 1/f₁(s)

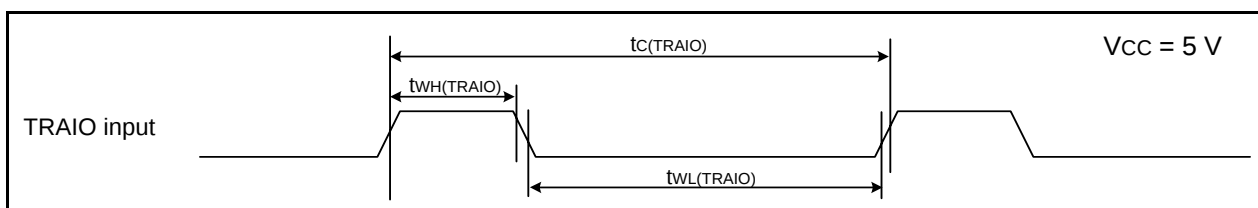
**Figure 5.7 I/O Timing of I²C bus Interface**

Timing Requirements**(Unless Otherwise Specified: $V_{CC} = 5\text{ V}$, $V_{SS} = 0\text{ V}$ at $T_{op} = 25^\circ\text{C}$) [$V_{CC} = 5\text{ V}$]****Table 5.18 XIN Input, XCIN Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(XIN)}$	XIN input cycle time	50	–	ns
$t_{WH(XIN)}$	XIN input “H” width	25	–	ns
$t_{WL(XIN)}$	XIN input “L” width	25	–	ns
$t_{c(XCIN)}$	XCIN input cycle time	14	–	μs
$t_{WH(XCIN)}$	XCIN input “H” width	7	–	μs
$t_{WL(XCIN)}$	XCIN input “L” width	7	–	μs

**Figure 5.8 XIN Input and XCIN Input Timing Diagram when $V_{CC} = 5\text{ V}$** **Table 5.19 TRAIO Input, $\overline{\text{INT1}}$ Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRAIO)}$	TRAIO input cycle time	100	–	ns
$t_{WH(TRAIO)}$	TRAIO input “H” width	40	–	ns
$t_{WL(TRAIO)}$	TRAIO input “L” width	40	–	ns

**Figure 5.9 TRAIO Input and $\overline{\text{INT1}}$ Input Timing Diagram when $V_{CC} = 5\text{ V}$** **Table 5.20 TRFI Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRFI)}$	TRFI input cycle time	400 ⁽¹⁾	–	ns
$t_{WH(TRFI)}$	TRFI input “H” width	200 ⁽²⁾	–	ns
$t_{WL(TRFI)}$	TRFI input “L” width	200 ⁽²⁾	–	ns

NOTES:

1. When using timer RF input capture mode, adjust the cycle time to $(1/\text{timer RF count source frequency} \times 3)$ or above.
2. When using timer RF input capture mode, adjust the pulse width to $(1/\text{timer RF count source frequency} \times 1.5)$ or above.

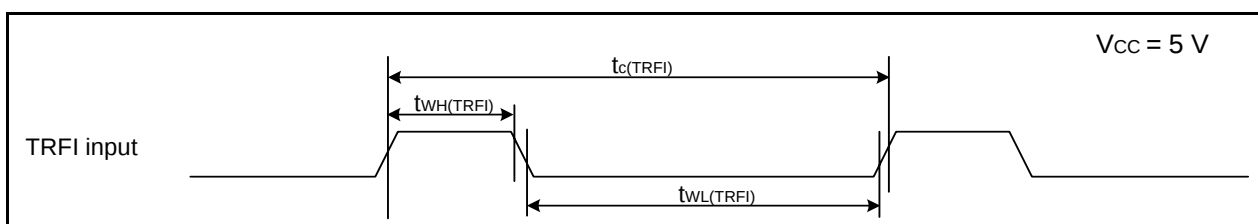
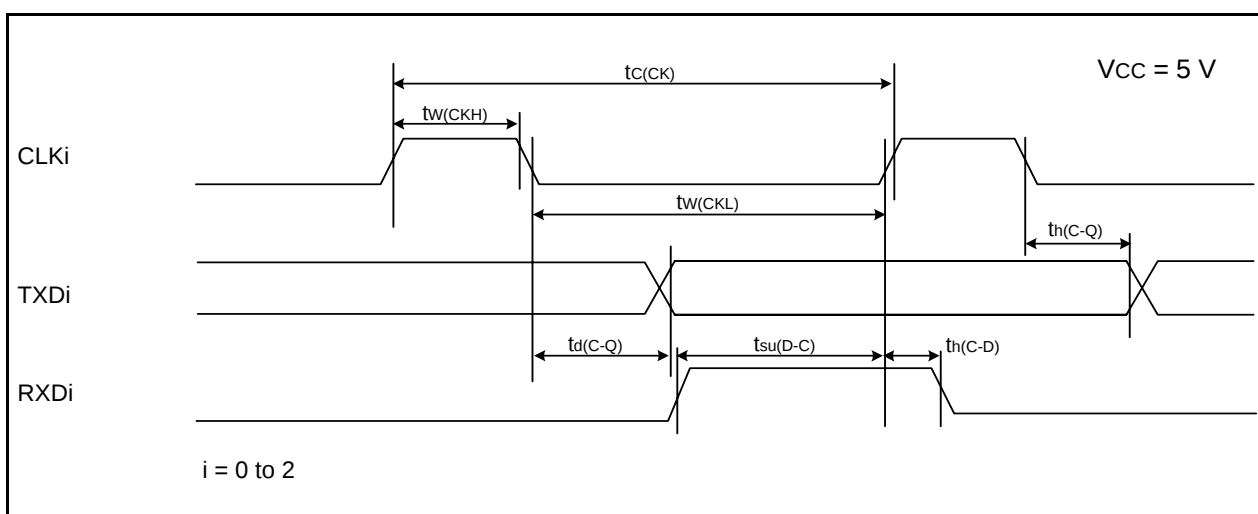
**Figure 5.10 TRFI Input Timing Diagram when $V_{CC} = 5\text{ V}$**

Table 5.21 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	200	—	ns
$t_{w(CKH)}$	CLKi input "H" width	100	—	ns
$t_{w(CKL)}$	CLKi input "L" width	100	—	ns
$t_{d(C-Q)}$	TXDi output delay time	—	50	ns
$t_{h(C-Q)}$	TXDi hold time	0	—	ns
$t_{su(D-C)}$	RXDi input setup time	50	—	ns
$t_{h(C-D)}$	RXDi input hold time	90	—	ns

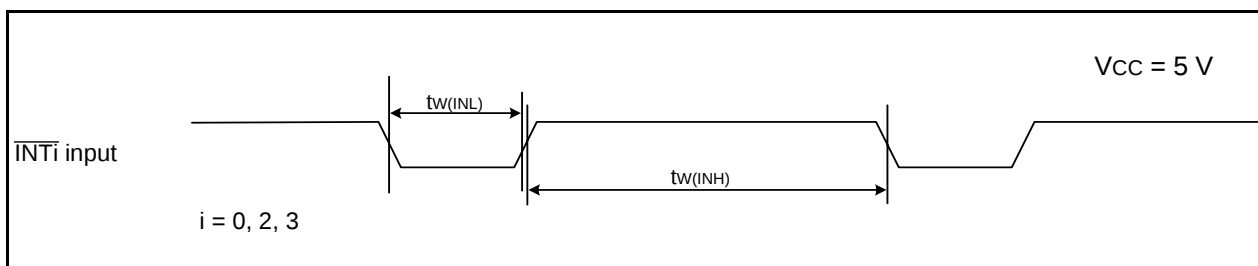
i = 0 to 2

**Figure 5.11 Serial Interface Timing Diagram when Vcc = 5 V****Table 5.22 External Interrupt $\overline{INTi}$ (i = 0, 2, 3) Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	$\overline{INT0}$ input "H" width	250 ⁽¹⁾	—	ns
$t_{w(INL)}$	$\overline{INT0}$ input "L" width	250 ⁽²⁾	—	ns

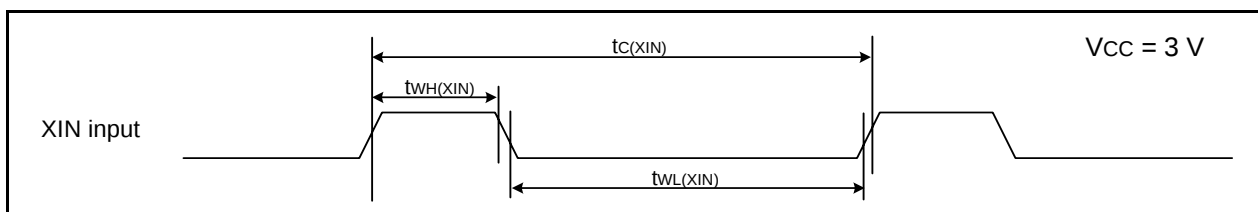
NOTES:

1. When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use an $\overline{INTi}$ input HIGH width of either (1/digital filter clock frequency × 3) or the minimum value of standard, whichever is greater.
2. When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use an $\overline{INTi}$ input LOW width of either (1/digital filter clock frequency × 3) or the minimum value of standard, whichever is greater.

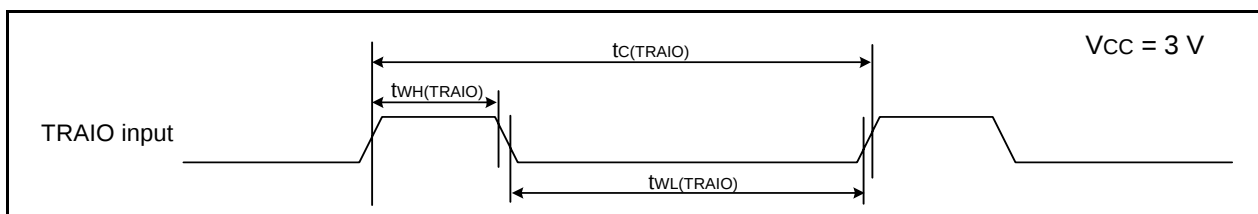
**Figure 5.12 External Interrupt $\overline{INTi}$ Input Timing Diagram when Vcc = 5 V**

Timing requirements**(Unless Otherwise Specified: $V_{CC} = 3\text{ V}$, $V_{SS} = 0\text{ V}$ at $T_{op} = 25^\circ\text{C}$) [$V_{CC} = 3\text{ V}$]****Table 5.25 XIN Input, XCIN Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(XIN)}$	XIN input cycle time	100	–	ns
$t_{WH(XIN)}$	XIN input “H” width	40	–	ns
$t_{WL(XIN)}$	XIN input “L” width	40	–	ns
$t_{c(XCIN)}$	XCIN input cycle time	14	–	μs
$t_{WH(XCIN)}$	XCIN input “H” width	7	–	μs
$t_{WL(XCIN)}$	XCIN input “L” width	7	–	μs

**Figure 5.13 XIN Input and XCIN Input Timing Diagram when $V_{CC} = 3\text{ V}$** **Table 5.26 TRAIO Input, $\overline{\text{INT1}}$ Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRAIO)}$	TRAIO input cycle time	300	–	ns
$t_{WH(TRAIO)}$	TRAIO input “H” width	120	–	ns
$t_{WL(TRAIO)}$	TRAIO input “L” width	120	–	ns

**Figure 5.14 TRAIO Input and $\overline{\text{INT1}}$ Input Timing Diagram when $V_{CC} = 3\text{ V}$** **Table 5.27 TRFI Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRFI)}$	TRFI input cycle time	1200 ⁽¹⁾	–	ns
$t_{WH(TRFI)}$	TRFI input “H” width	600 ⁽²⁾	–	ns
$t_{WL(TRFI)}$	TRFI input “L” width	600 ⁽²⁾	–	ns

NOTES:

1. When using timer RF input capture mode, adjust the cycle time to $(1/\text{timer RF count source frequency} \times 3)$ or above.
2. When using timer RF input capture mode, adjust the pulse width to $(1/\text{timer RF count source frequency} \times 1.5)$ or above.

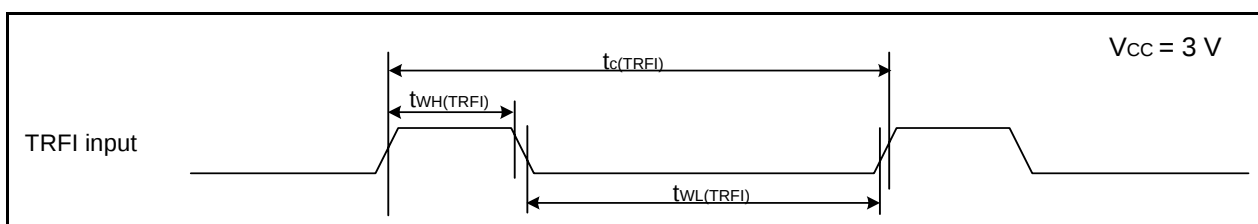
**Figure 5.15 TRFI Input Timing Diagram when $V_{CC} = 3\text{ V}$**

Table 5.30 Electrical Characteristics (5) [V_{CC} = 2.2 V]

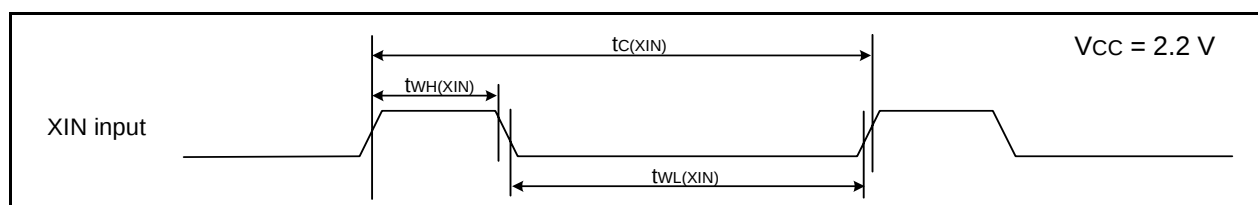
Symbol	Parameter		Condition		Standard			Unit
					Min.	Typ.	Max.	
V _{OH}	Output "H" voltage	Except P2_0 to P2_7, XOUT	I _{OH} = -1 mA		V _{CC} - 0.5	—	V _{CC}	V
		P2_0 to P2_7	Drive capacity HIGH	I _{OH} = -2 mA	V _{CC} - 0.5	—	V _{CC}	V
			Drive capacity LOW	I _{OH} = -1 mA	V _{CC} - 0.5	—	V _{CC}	V
		XOUT	Drive capacity HIGH	I _{OH} = -0.1 mA	V _{CC} - 0.5	—	V _{CC}	V
			Drive capacity LOW	I _{OH} = -50 μA	V _{CC} - 0.5	—	V _{CC}	V
V _{OL}	Output "L" voltage	Except P2_0 to P2_7, XOUT	I _{OL} = 1 mA		—	—	0.5	V
		P2_0 to P2_7	Drive capacity HIGH	I _{OL} = 2 mA	—	—	0.5	V
			Drive capacity LOW	I _{OL} = 1 mA	—	—	0.5	V
		XOUT	Drive capacity HIGH	I _{OL} = 0.1 mA	—	—	0.5	V
			Drive capacity LOW	I _{OL} = 50 μA	—	—	0.5	V
V _{T+} -V _{T-}	Hysteresis	INT0, INT1, INT2, INT3, KI0, KI1, KI2, KI3, TRAIO, TRFI, RXD0, RXD1, CLK0, CLK1, CLK2, SSI, SCL, SDA, SSO			0.05	0.3	—	V
		RESET			0.05	0.15	—	V
I _{IH}	Input "H" current		V _I = 2.2 V		—	—	4.0	μA
I _{IL}	Input "L" current		V _I = 0 V		—	—	-4.0	μA
R _{PULLUP}	Pull-up resistance		V _I = 0 V		100	200	600	kΩ
R _{IXIN}	Feedback resistance	XIN			—	5	—	MΩ
R _{IXCIN}	Feedback resistance	XCIN			—	35	—	MΩ
V _{RAM}	RAM hold voltage		During stop mode		1.8	—	—	V

NOTE:

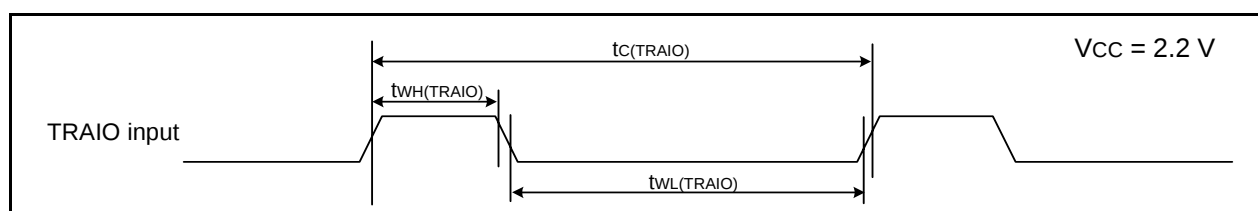
- V_{CC} = 2.2 V at T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), f(XIN) = 5 MHz, unless otherwise specified.

Timing requirements**(Unless Otherwise Specified: $V_{CC} = 2.2\text{ V}$, $V_{SS} = 0\text{ V}$ at $T_{opr} = 25^\circ\text{C}$) [$V_{CC} = 2.2\text{ V}$]****Table 5.32 XIN Input, XCIN Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(XIN)}$	XIN input cycle time	200	–	ns
$t_{WH(XIN)}$	XIN input “H” width	90	–	ns
$t_{WL(XIN)}$	XIN input “L” width	90	–	ns
$t_{c(XCIN)}$	XCIN input cycle time	14	–	μs
$t_{WH(XCIN)}$	XCIN input “H” width	7	–	μs
$t_{WL(XCIN)}$	XCIN input “L” width	7	–	μs

**Figure 5.18 XIN Input and XCIN Input Timing Diagram when $V_{CC} = 2.2\text{ V}$** **Table 5.33 TRAIO Input, $\overline{\text{INT1}}$ Input**

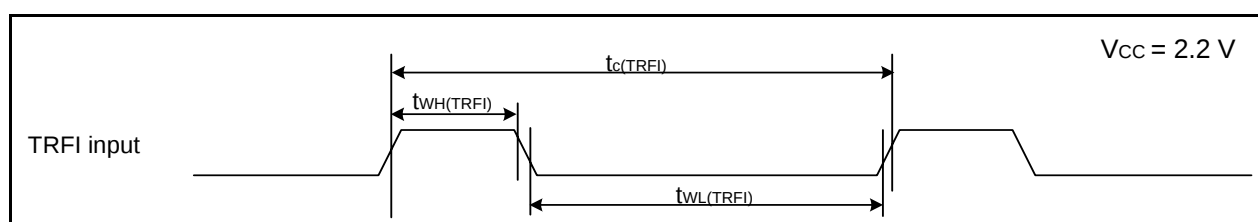
Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRAIO)}$	TRAIO input cycle time	500	–	ns
$t_{WH(TRAIO)}$	TRAIO input “H” width	200	–	ns
$t_{WL(TRAIO)}$	TRAIO input “L” width	200	–	ns

**Figure 5.19 TRAIO Input and $\overline{\text{INT1}}$ Input Timing Diagram when $V_{CC} = 2.2\text{ V}$** **Table 5.34 TRFI Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRFI)}$	TRFI input cycle time	2000 ⁽¹⁾	–	ns
$t_{WH(TRFI)}$	TRFI input “H” width	1000 ⁽²⁾	–	ns
$t_{WL(TRFI)}$	TRFI input “L” width	1000 ⁽²⁾	–	ns

NOTES:

1. When using timer RF input capture mode, adjust the cycle time to $(1/\text{timer RF count source frequency} \times 3)$ or above.
2. When using timer RF input capture mode, adjust the pulse width to $(1/\text{timer RF count source frequency} \times 1.5)$ or above.

**Figure 5.20 TRFI Input Timing Diagram when $V_{CC} = 2.2\text{ V}$**

REVISION HISTORY	R8C/2C Group, R8C/2D Group Datasheet
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Rev.	Date	Description	
		Page	Summary
0.01	Apr 03, 2006	–	First Edition issued
0.10	Jun 26, 2006	All pages	Pin name revised CMP0_0 → TRFO00, CMP0_1 → TRFO01, CMP0_2 → TRFO02, CMP1_0 → TRFO10, CMP1_1 → TRFO11, CMP1_2 → TRFO12, TRFIN → TRFI
		2, 4	Table 1.1 Specifications for R8C/2C Group (1) and Table 1.3 Specifications for R8C/2D Group (1); I/O Ports: • Input-only: 3 pins → 2 pins revised Interrupts: • Internal: 17 sources → 23 sources revised
		3, 5	Table 1.2 Specifications for R8C/2C Group (2) and Table 1.4 Specifications for R8C/2D Group (2); ROM Correction Function deleted
		8	Figure 1.3 Block Diagram revised
		9	Figure 1.4 Pin Assignment (Top View) revised
		10, 11	Table 1.7 Pin Name Information by Pin Number (1) and Table 1.8 Pin Name Information by Pin Number (2) revised
		12, 13	Table 1.9 Pin Functions (1) and Table 1.10 Pin Functions (2) revised
		19	Table 4.1 SFR Information (1); • 0008h: Module Standby Control Register, MSTCR, 00h added • 001Ch: “00h” → “00h, 10000000b” revised • NOTE6 added
		20	Table 4.2 SFR Information (2); • 005Fh: Capture Interrupt Control Register, CAPIC, XXXXX000b added
		22	Table 4.4 SFR Information (4); • 00DCh: “00DDh” → “00DCh” revised • 00F5h: “XXXX00XXb” → “00h” revised
		23	Table 4.5 SFR Information (5); • 0105h: LIN Special Function Register, LINCR2, 00h added
		31	Package Dimensions; “Diagrams showing the latest package dimensions ... in the “Packages” section of the Renesas Technology website.” added
0.20	Sep 15, 2006	31 to 54	5. Electrical Characteristics added
0.30	Dec 22, 2006	6	Table 1.5 and Figure 1.1 revised
		7	Table 1.6 and Figure 1.2 revised
		17	Figure 3.1 revised
		18	Figure 3.2 revised
		19	Table 4.1; • 000Ah: “00XXX000b” → “00h” revised • 0008h: “Module Standby Control Register” → “Module Operation Enable Register” revised • 000Fh: “00011111b” → “00X11111b” revised
		37	Table 5.11 revised

REVISION HISTORY	R8C/2C Group, R8C/2D Group Datasheet
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Rev.	Date	Description	
		Page	Summary
1.00	Feb 09, 2007	All pages	"Preliminary" deleted
		3	Table 1.2 revised
		5	Table 1.4 revised
		6	Table 1.5 and Figure 1.1 revised
		7	Table 1.6 and Figure 1.2 revised
		17	Figure 3.1 revised
		18	Figure 3.2 revised
		19	Table 4.1; • 0008h: "Module Standby Control Register" → "Module Operation Enable Register" revised • 000Ah: "00XXX000b" → "00h" revised • 000Fh: "00011111b" → "00X11111b" revised • 002Bh: "High-Speed On-Chip Oscillator Control Register 6" added
		23	Table 4.5; 0105h: "LIN Control Register 2" register name revised
		31	Table 5.2 revised
		32	Table 5.3 and Table 5.4; NOTE1 revised
		37	Table 5.11 revised
		44	Table 5.17 revised
		46	Table 5.21 and Figure 5.11; "i = 0 to 2" revised
		48	Table 5.24 revised
		50	Table 5.28 revised, Figure 5.16; "i = 0 to 2" revised
		52	Table 5.31 revised
		53	Table 5.34 revised
		54	Table 5.35 and Figure 5.21; "i = 0 to 2" revised
2.00	Oct 17, 2007	all pages	Y version added
		6, 7	Table 1.5, Table 1.6 (D) mark is deleted
		31	Table 5.1 Rated Value: "TBD" → "700"
2.10	Dec 05, 2007	2, 4	Table 1.1, Table 1.3 Clock: "Real-time clock (timer RE)" added
		6, 7	Table 1.5 and Figure 1.1 revised
		8	Table 1.6 and Figure 1.2 revised
		18, 19	Figure 3.1 and Figure 3.2 revised
		20	Table 4.1 002Ch: High-Speed On-Chip Oscillator Control Register 7 added
		23	Table 4.4 00F5h: After reset "00h" → "000000XXb" revised
		33	Table 5.2 NOTE2 revised
		39	Table 5.11 revised

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